

Title (en)
ELECTRONIC CIRCUIT MODULE

Title (de)
ELEKTRONISCHES SCHALTUNGSMODUL

Title (fr)
MODULE DE CIRCUIT ÉLECTRONIQUE

Publication
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Application
EP 21749564 A 20210722

Priority
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Abstract (en)
[origin: WO2022028915A1] The invention relates to an electronic circuit module (1) having a multilayered LTCC circuit carrier (20) made of structured inorganic substrate layers (22) which have electrical and/or thermal conduction structures for electrical and/or thermal conduction, at least one electronic component (5) which is arranged on one first side (20.1) and/or an opposite second side (20.2) of the LTCC circuit carrier (20), and at least one SiC power semiconductor (7). The at least one SiC power semiconductor (7) is embedded in the multilayered LTCC circuit carrier (20) and is enclosed at least on three sides by the multilayered LTCC circuit carrier (20), wherein connection contacts of the SiC power semiconductor (7) contact the electrical and/or thermal conduction structures of the LTCC circuit carrier (20).

IPC 8 full level
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BA ME

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